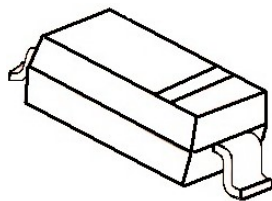


SOD-323



特征 Features

- 齐纳击穿阻抗低; Low Zener Impedance
- 最大功率耗散 200mW; Power Dissipation of 200mW
- 高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

- 封装: SOD-323 封装 SOD-323 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
功率消耗 Power Dissipation	Pd	200 ¹⁾	mW
正向压降 Forward Voltage @IF=10mA	Vf	0.9 ²⁾	V
存储温度 Storage temperature range	Ts	-65-+150	°C

1) Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm²

2) Short duration test pulse used to minimize self-heating effect

3) f=1KHz

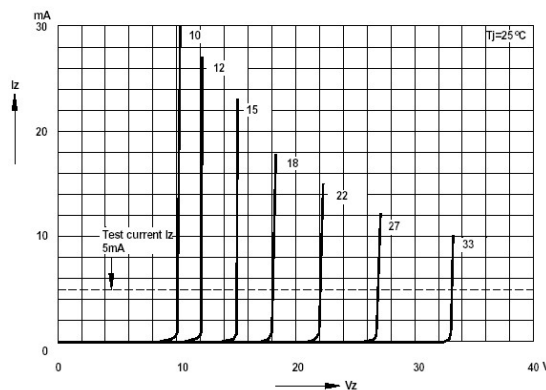
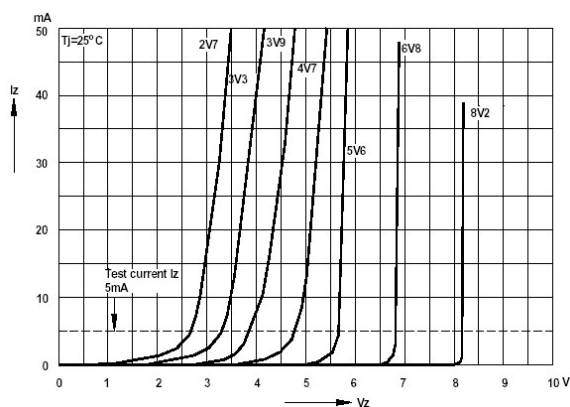
电特性 (TA = 25°C 除非另有规定)

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

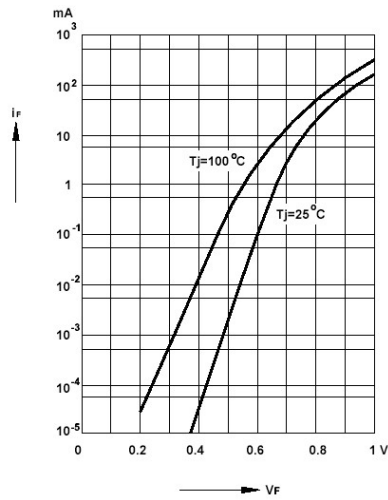
Device	Marking	Zener Voltage Range				Maximum Zener Impedance ³⁾			Maximum Reverse Current		Typical Temperature coefficient @ IZTC=mV/°C		Test Current IZTC
		Vz@Izt			Izt	Zzt @Izt	Zzk @Izk	Izk	IR	VR	Min	Max	
		Nom(V)	Min(V)	Max(V)	mA	Ω		mA	uA	V			mA
MM3Z10VT1G-CN	WF	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0	5

Breakdown characteristics

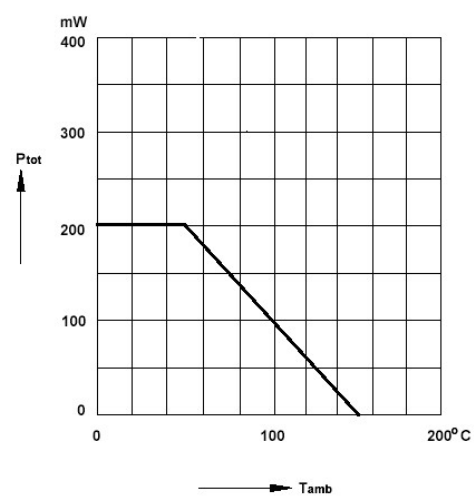
at Tj=constant (pulsed)



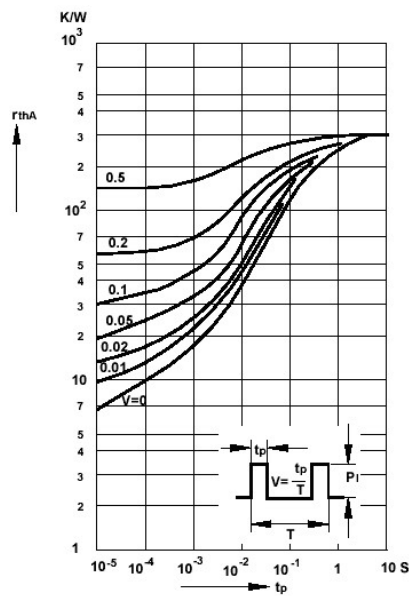
Forward characteristics



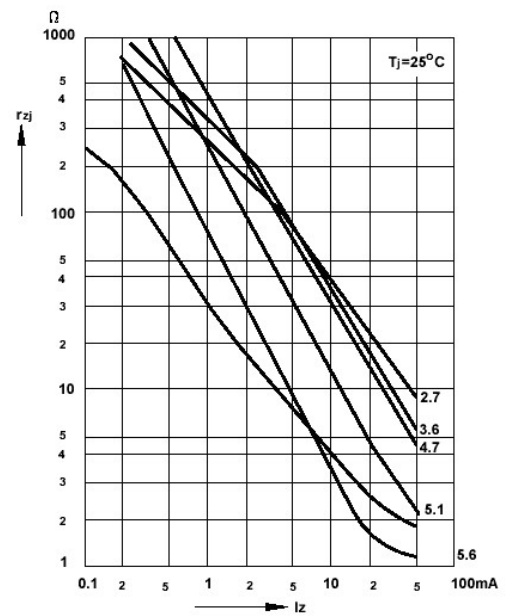
Admissible power dissipation versus ambient temperature



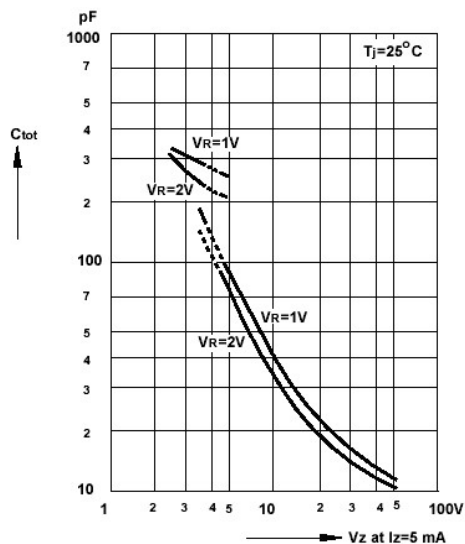
Pulse thermal resistance versus pulse duration



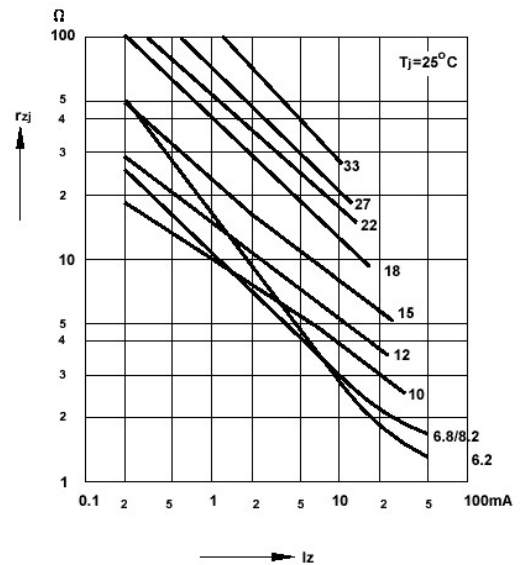
Dynamic resistance versus Zener current

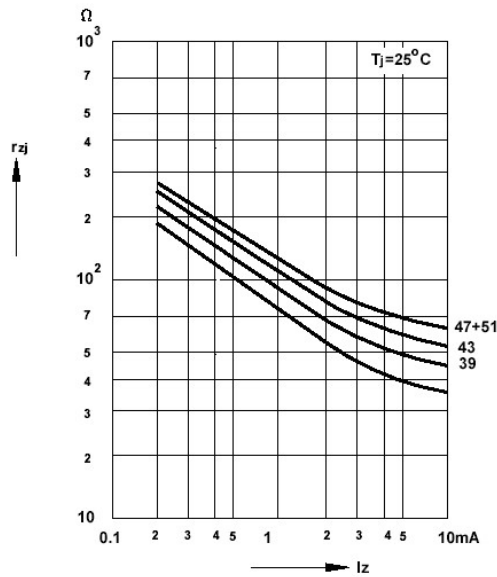
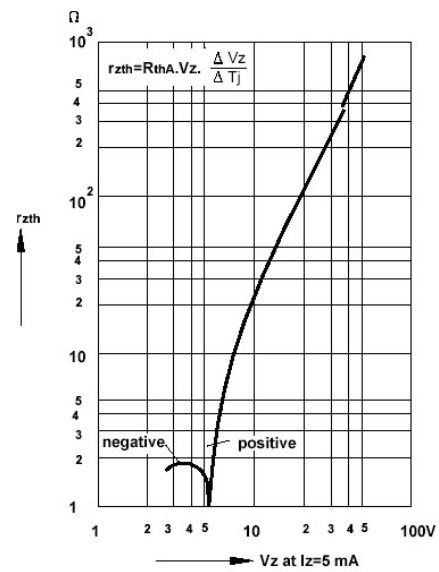
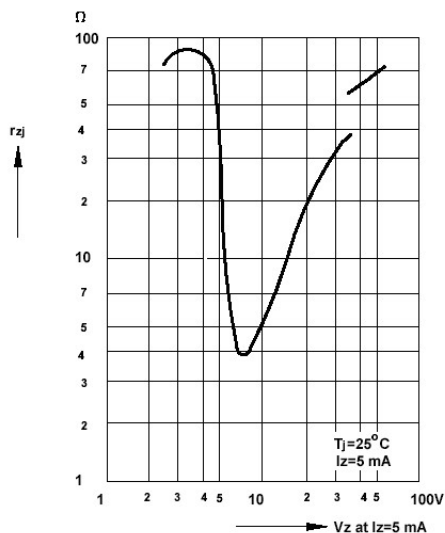
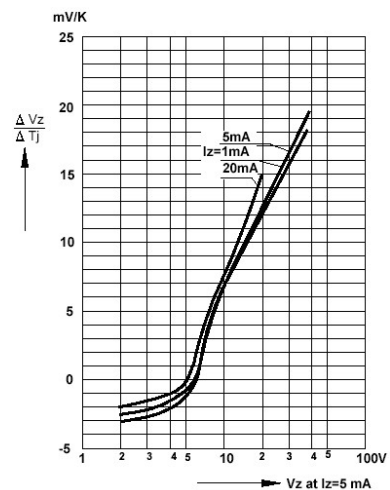
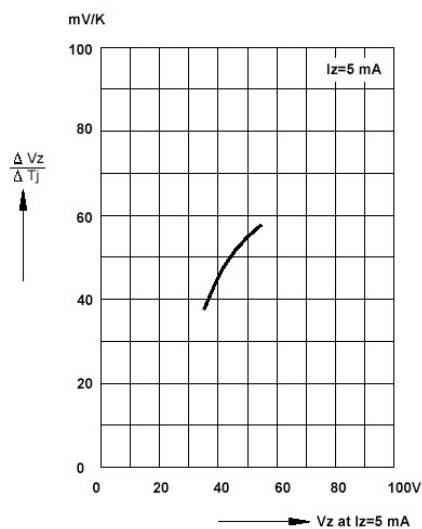
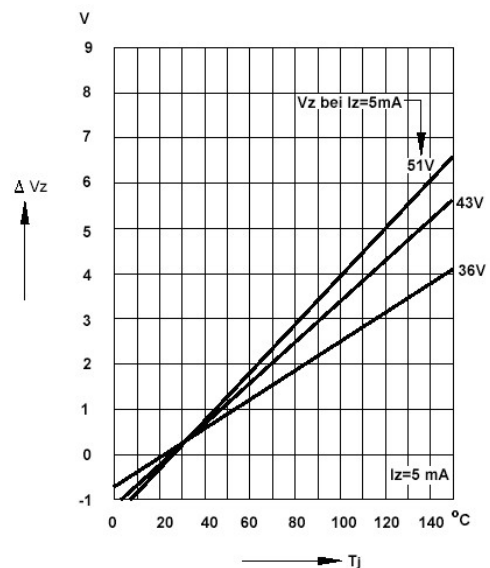


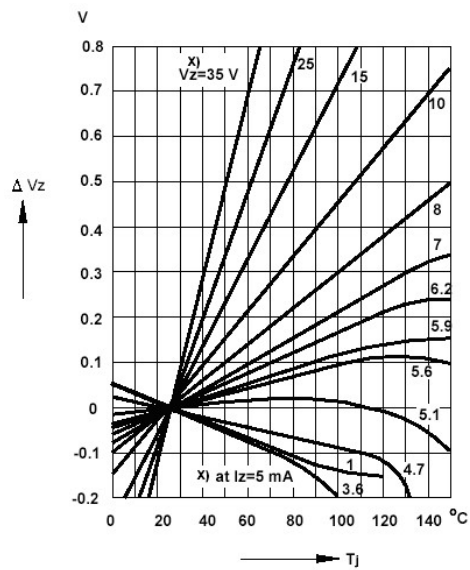
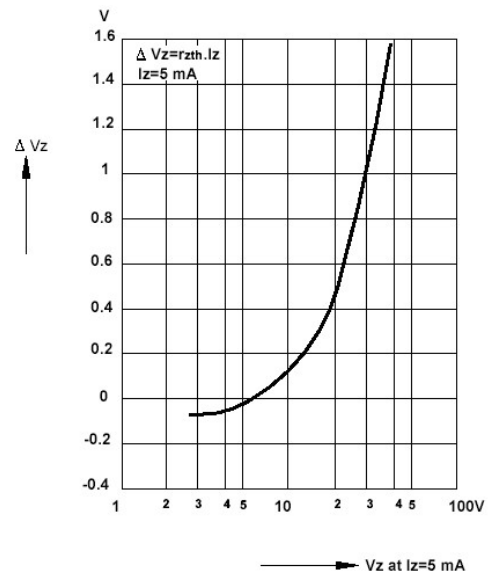
Capacitance versus Zener voltage

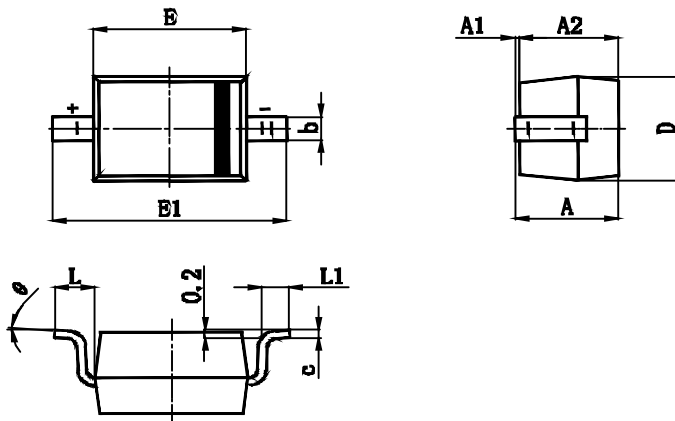


Dynamic resistance versus Zener current



Dynamic resistance versus Zener current

Thermal differential resistance versus Zener voltage

Dynamic resistance versus Zener voltage

Temperature dependence of Zener voltage versus Zener voltage

Temperature dependence of Zener voltage versus Zener voltage

Change of Zener voltage versus junction temperature


Change of Zener voltage versus junction temperature

Change of Zener voltage from turn-on up to the point of thermal equilibrium versus Zener voltage

SOD-323 PACKAGE OUTLINE Plastic surface mounted package

SOD-323


Symbol	Min.(mm)	Max.(mm)
A		1.000
A1	0.000	0.100
A2	0.800	0.900
b	0.250	0.350
c	0.080	0.150
D	1.200	1.400
E	1.600	1.800
E1	2.500	2.700
L	0.475REF	
L1	0.250	0.400
θ	0 $^{\circ}$	8 $^{\circ}$

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